BUL45D2G

High Speed, High Gain Bipolar NPN Power Transistor

with Integrated Collector−Emitter Diode and Built−in Efficient Antisaturation Network

The BUL45D2G is state−of−art High Speed High gain BiPolar transistor (H2BIP). High dynamic characteristics and lot−to−lot minimum spread (±150 ns on storage time) make it ideally suitable for light ballast applications. Therefore, there is no need to guarantee an h_{FE} window. It’s characteristics make it also suitable for PFC application.

Features

- Low Base Drive Requirement
- High Peak DC Current Gain
- Extremely Low Storage Time Min/Max Guarantees Due to the H2BIP Structure which Minimizes the Spread
- Integrated Collector−Emitter Free Wheeling Diode
- Fully Characterized and Guaranteed Dynamic $V_{CE(sat)}$
- “6 Sigma” Process Providing Tight and Reproductible Parameter Spreads
- These Devices are Pb−Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector−Emitter Sustaining Voltage	V_{CEO}	400	Vdc
Collector−Base Breakdown Voltage	V_{CBO}	700	Vdc
Collector−Emitter Breakdown Voltage	V_{CES}	700	Vdc
Emitter−Base Voltage	V_{EBO}	12	Vdc
Collector Current − Continuous	I_C	5	Adc
Collector Current − Peak (Note 1)	I_{CM}	10	Adc
Base Current − Continuous	I_B	2	Adc
Base Current − Peak (Note 1)	I_{BM}	4	Adc
Total Device Dissipation @ T_C = 25°C Derate above 25°C	P_D	 75 0.6	 W W/°C
Operating and Storage Temperature	T_J, T_{stg}	−65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

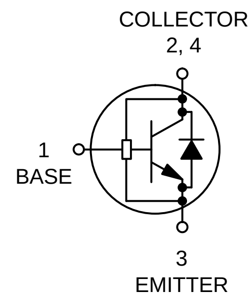
1. Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.

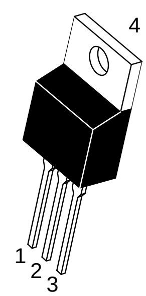
*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor®

www.onsemi.com

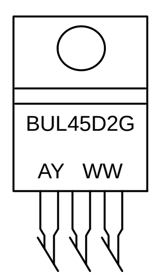
POWER TRANSISTOR
5.0 AMPERES,
700 VOLTS, 75 WATTS





TO−220
CASE 221A
STYLE 1

MARKING DIAGRAM



A	= Assembly Location
Y	= Year
WW	= Work Week
G	= Pb−Free Package

ORDERING INFORMATION

Device	Package	Shipping
BUL45D2G	TO−220 (Pb−Free)	50 Units / Rail

THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	1.65	°C/W
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	62.5	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8″ from Case for 5 Seconds	T_L	260	°C

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector−Emitter Sustaining Voltage (I_C = 100 mA, L = 25 mH)	$V_{CEO(sus)}$	400	450	−	Vdc
Collector−Base Breakdown Voltage (I_{CBO} = 1 mA)	V_{CBO}	700	910	−	Vdc
Emitter−Base Breakdown Voltage (I_{EBO} = 1 mA)	V_{EBO}	12	14.1	−	Vdc
Collector Cutoff Current (V_{CE} = Rated V_{CEO}, I_B = 0)	I_{CEO}	−	−	100	µAdc
Collector Cutoff Current (V_{CE} = Rated V_{CES}, V_{EB} = 0) @ T_C = 25°C @ T_C = 125°C (V_{CE} = 500 V, V_{EB} = 0) @ T_C = 125°C	I_{CES}	 − − −	 − − −	 100 500 100	µAdc
Emitter−Cutoff Current (V_{EB} = 10 Vdc, I_C = 0)	I_{EBO}	−	−	100	µAdc
ON CHARACTERISTICS					
Base−Emitter Saturation Voltage (I_C = 0.8 Adc, I_B = 80 mAdc) @ T_C = 25°C @ T_C = 125°C (I_C = 2 Adc, I_B = 0.4 Adc) @ T_C = 25°C @ T_C = 125°C	$V_{BE(sat)}$	 − − − −	 0.8 0.7 0.89 0.79	 1 0.9 1 0.9	Vdc
Collector−Emitter Saturation Voltage (I_C = 0.8 Adc, I_B = 80 mAdc) @ T_C = 25°C @ T_C = 125°C (I_C = 2 Adc, I_B = 0.4 Adc) @ T_C = 25°C @ T_C = 125°C (I_C = 0.8 Adc, I_B = 40 mAdc) @ T_C = 25°C @ T_C = 125°C	$V_{CE(sat)}$	 − − − − − −	 0.28 0.32 0.32 0.38 0.46 0.62	 0.4 0.5 0.5 0.6 0.75 1	Vdc
DC Current Gain (I_C = 0.8 Adc, V_{CE} = 1 Vdc) @ T_C = 25°C @ T_C = 125°C (I_C = 2 Adc, V_{CE} = 1 Vdc) @ T_C = 25°C @ T_C = 125°C	h_{FE}	 22 20 10 7	 34 29 14 9.5	 − − − −	−
DIODE CHARACTERISTICS					
Forward Diode Voltage (I_{EC} = 1 Adc) @ T_C = 25°C @ T_C = 125°C (I_{EC} = 2 Adc) @ T_C = 25°C @ T_C = 125°C (I_{EC} = 0.4 Adc) @ T_C = 25°C @ T_C = 125°C	V_{EC}	 − − − − − −	 1.04 0.7 1.2 − 0.85 0.62	 1.5 − 1.6 − 1.2 −	V

ELECTRICAL CHARACTERISTICS (continued) (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
DIODE CHARACTERISTICS					
Forward Recovery Time (see Figure 27)	T_{fr}				ns
(I_F = 1 Adc, di/dt = 10 A/μs) @ T_C = 25°C		–	330	–	
(I_F = 2 Adc, di/dt = 10 A/μs) @ T_C = 25°C		–	360	–	
(I_F = 0.4 Adc, di/dt = 10 A/μs) @ T_C = 25°C		–	320	–	
DYNAMIC CHARACTERISTICS					
Current Gain Bandwidth (I_C = 0.5 Adc, V_{CE} = 10 Vdc, f = 1 MHz)	f_T	–	13	–	MHz
Output Capacitance (V_{CB} = 10 Vdc, I_E = 0, f = 1 MHz)	C_{ob}	–	50	75	pF
Input Capacitance (V_{EB} = 8 Vdc)	C_{ib}	–	340	500	pF

DYNAMIC SATURATION VOLTAGE

Characteristic	Conditions	Time	Temperature	Symbol	Min	Typ	Max	Unit
Dynamic Saturation Voltage: Determined 1 μs and 3 μs respectively after rising I_{B1} reaches 90% of final I_{B1}	I_C = 1 A I_{B1} = 100 mA V_{CC} = 300 V	@ 1 μs	@ T_C = 25°C @ T_C = 125°C	$V_{CE(dsat)}$	– –	3.7 9.4	– –	V
		@ 3 μs	@ T_C = 25°C @ T_C = 125°C		– –	0.35 2.7	– –	V
	I_C = 2 A I_{B1} = 0.8 A V_{CC} = 300 V	@ 1 μs	@ T_C = 25°C @ T_C = 125°C		– –	3.9 12	– –	V
		@ 3 μs	@ T_C = 25°C @ T_C = 125°C		– –	0.4 1.5	– –	V

SWITCHING CHARACTERISTICS: Resistive Load (D.C. ≤ 10%, Pulse Width = 20 μs)

Characteristic	Conditions	Temperature	Symbol	Min	Typ	Max	Unit
Turn−on Time	I_C = 2 Adc, I_{B1} = 0.4 Adc I_{B2} = 1 Adc V_{CC} = 300 Vdc	@ T_C = 25°C @ T_C = 125°C	t_{on}	– –	90 105	150 –	ns
Turn−off Time		@ T_C = 25°C @ T_C = 125°C	t_{off}	– –	1.15 1.5	1.3 –	μs
Turn−on Time	I_C = 2 Adc, I_{B1} = 0.4 Adc I_{B2} = 0.4 Adc V_{CC} = 300 Vdc	@ T_C = 25°C @ T_C = 125°C	t_{on}	– –	90 110	150 –	ns
Turn−off Time		@ T_C = 25°C @ T_C = 125°C	t_{off}	2.1 –	– 3.1	2.4 –	μs

SWITCHING CHARACTERISTICS: Inductive Load (V_{clamp} = 300 V, V_{CC} = 15 V, L = 200 μH)

Characteristic	Conditions	Temperature	Symbol	Min	Typ	Max	Unit
Fall Time	I_C = 1 Adc I_{B1} = 100 mAdc I_{B2} = 500 mAdc	@ T_C = 25°C @ T_C = 125°C	t_f	– –	90 93	150 –	ns
Storage Time		@ T_C = 25°C @ T_C = 125°C	t_s	– –	0.72 1.05	0.9 –	μs
Crossover Time		@ T_C = 25°C @ T_C = 125°C	t_c	– –	95 95	150 –	ns
Fall Time	I_C = 2 Adc I_{B1} = 0.4 Adc I_{B2} = 0.4 Adc	@ T_C = 25°C @ T_C = 125°C	t_f	– –	80 105	150 –	ns
Storage Time		@ T_C = 25°C @ T_C = 125°C	t_s	1.95 –	– 2.9	2.25 –	μs
Crossover Time		@ T_C = 25°C @ T_C = 125°C	t_c	– –	225 450	300 –	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL STATIC CHARACTERISTICS

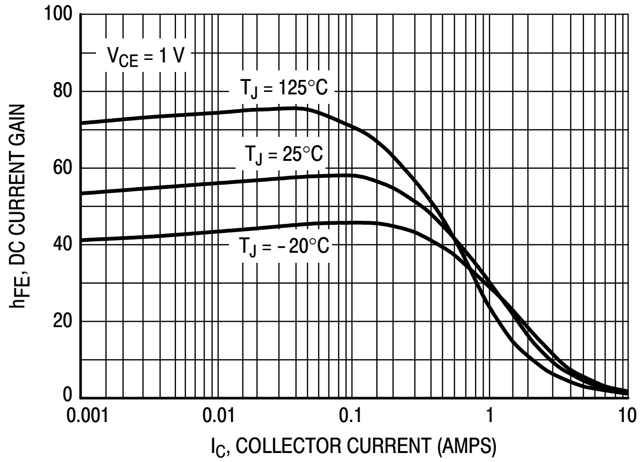


Figure 1. DC Current Gain @ 1 Volt

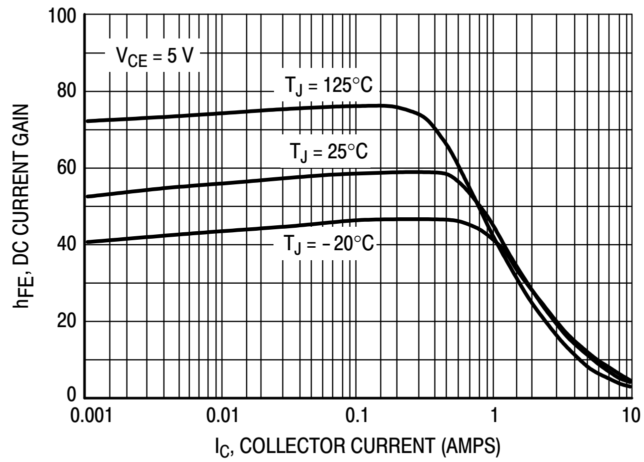


Figure 2. DC Current Gain @ 5 Volt

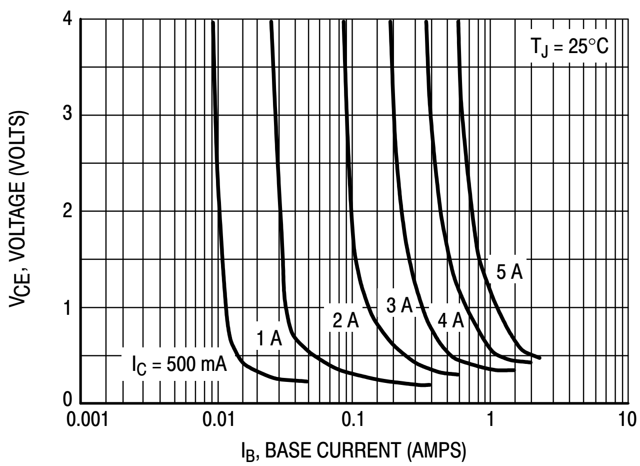


Figure 3. Collector Saturation Region

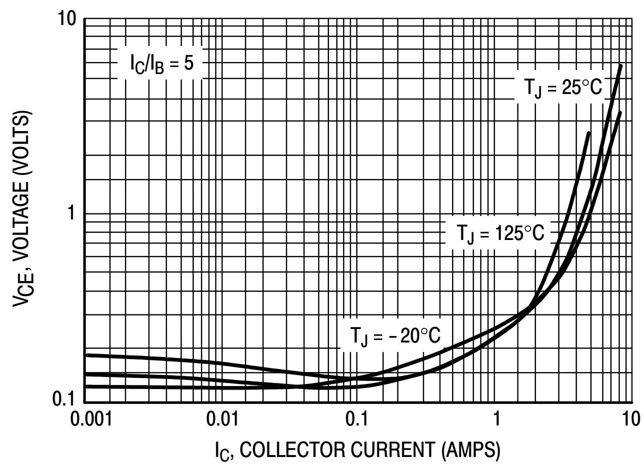


Figure 4. Collector−Emitter Saturation Voltage

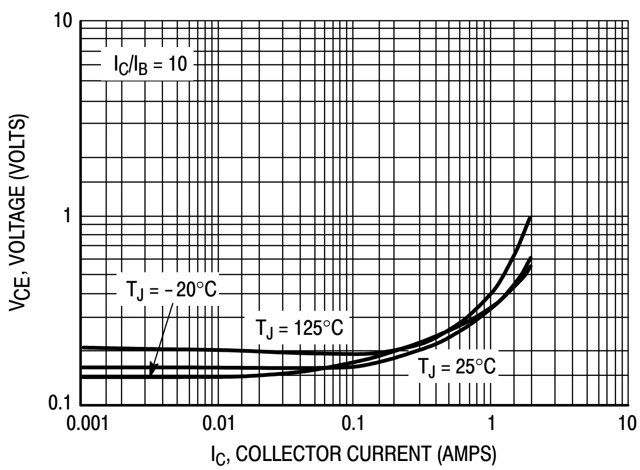


Figure 5. Collector−Emitter Saturation Voltage

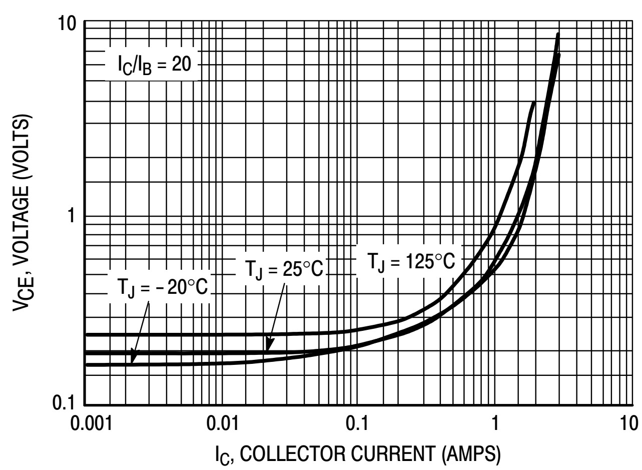


Figure 6. Collector−Emitter Saturation Voltage

TYPICAL STATIC CHARACTERISTICS

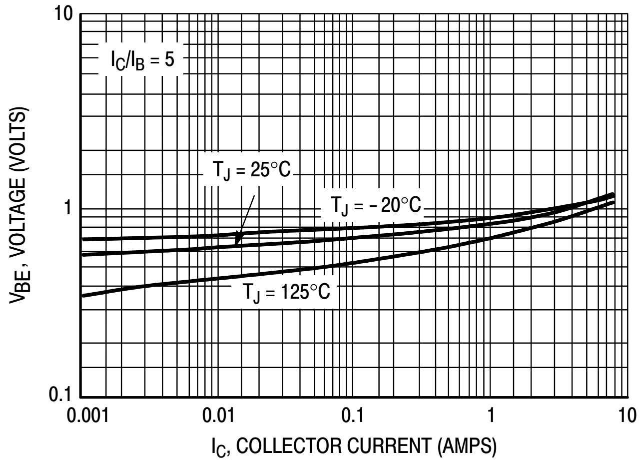


Figure 7. Base−Emitter Saturation Region

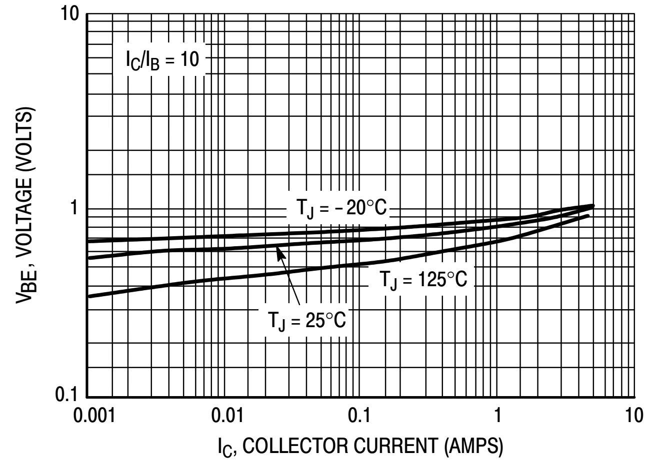


Figure 8. Base−Emitter Saturation Region

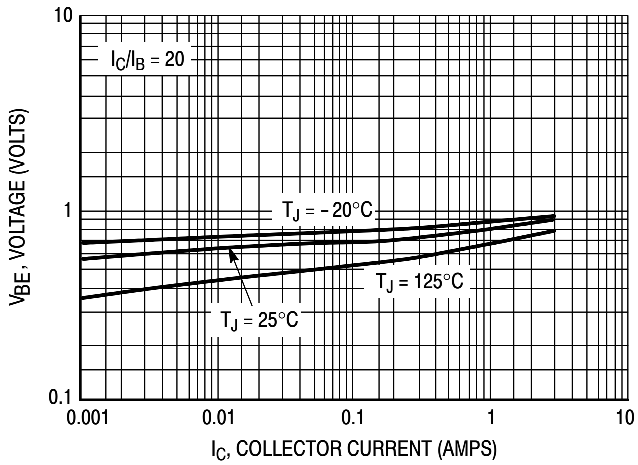


Figure 9. Base−Emitter Saturation Region

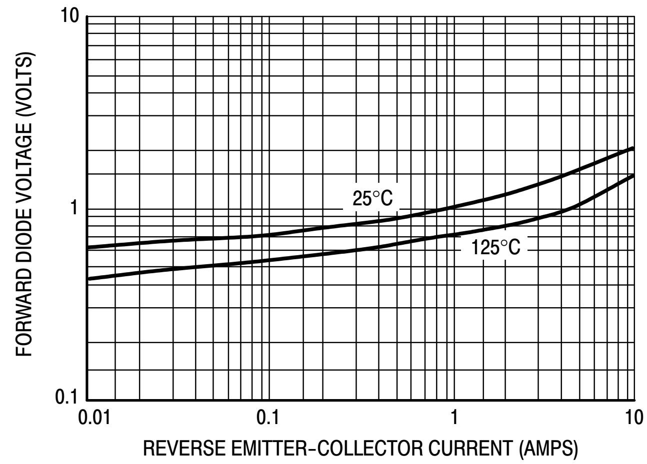


Figure 10. Forward Diode Voltage

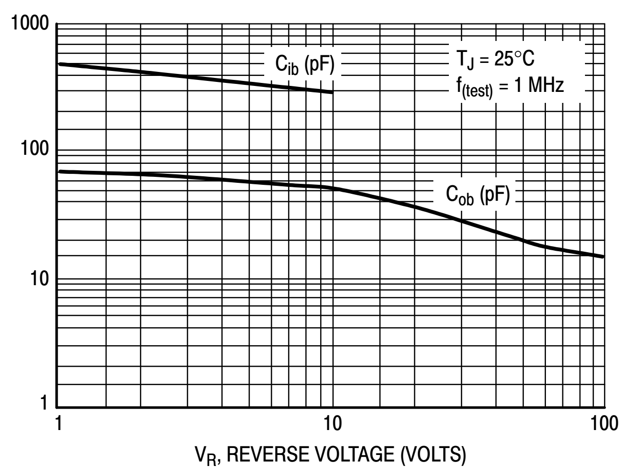


Figure 11. Capacitance

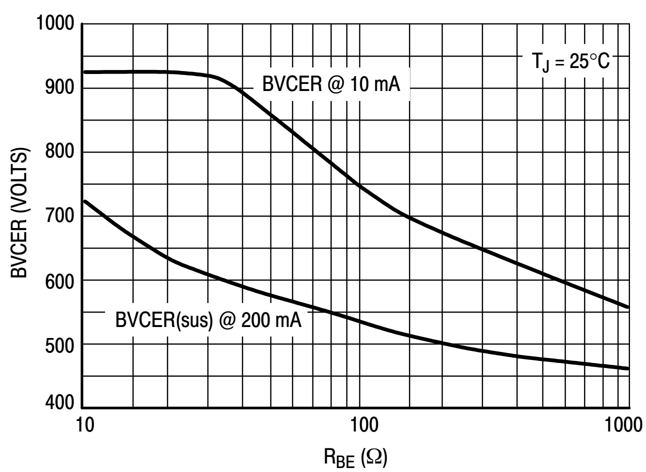


Figure 12. BVCER = f(ICER)

TYPICAL SWITCHING CHARACTERISTICS

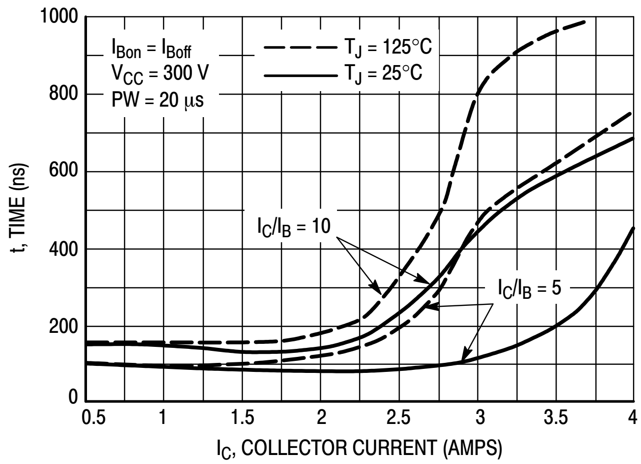


Figure 13. Resistive Switch Time, t_{on}

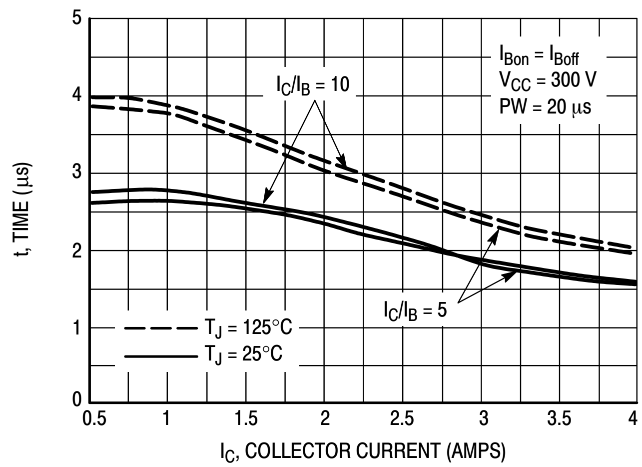


Figure 14. Resistive Switch Time, t_{off}

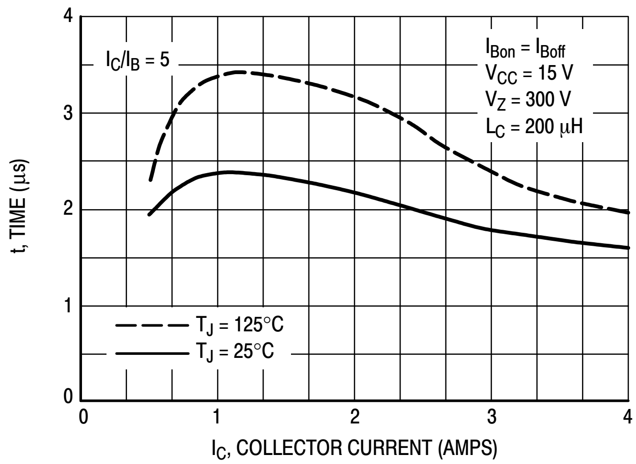


Figure 15. Inductive Storage Time, t_{si} @ I_C/I_B = 5

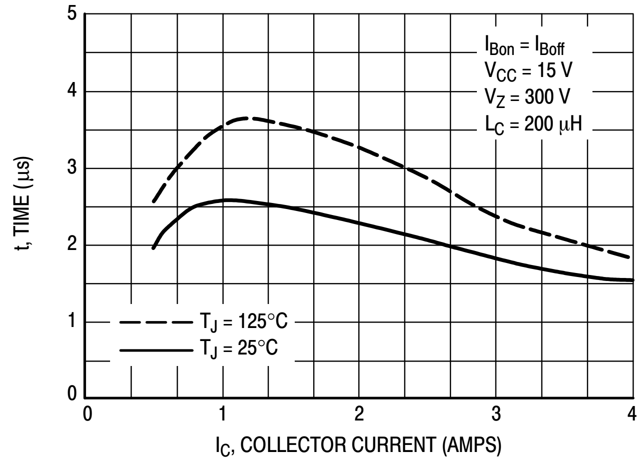


Figure 16. Inductive Storage Time, t_{si} @ I_C/I_B = 10

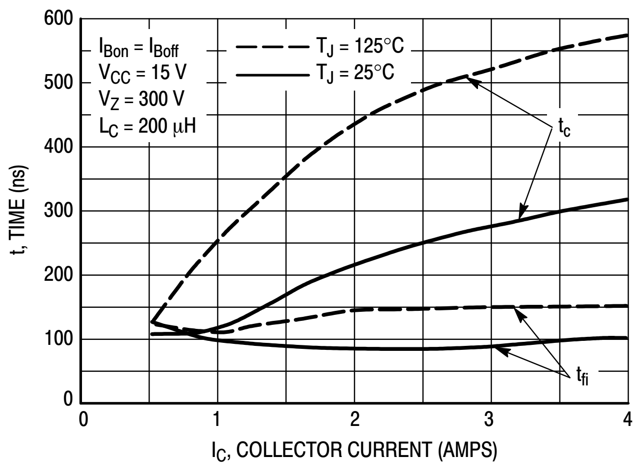


Figure 17. Inductive Switching, t_c & t_{fi} @ I_C/I_B = 5

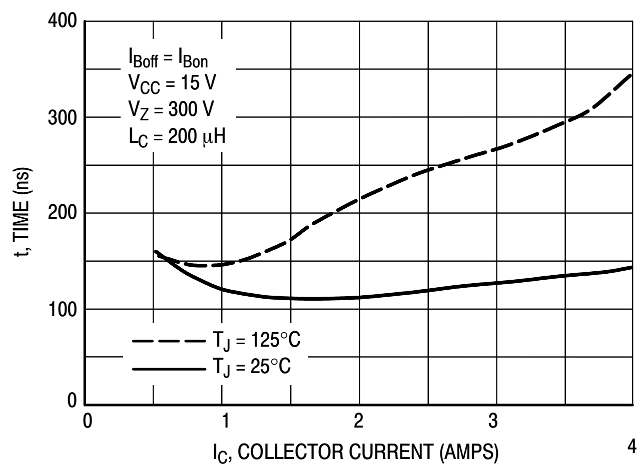


Figure 18. Inductive Switching, t_{fi} @ I_C/I_B = 10

TYPICAL SWITCHING CHARACTERISTICS

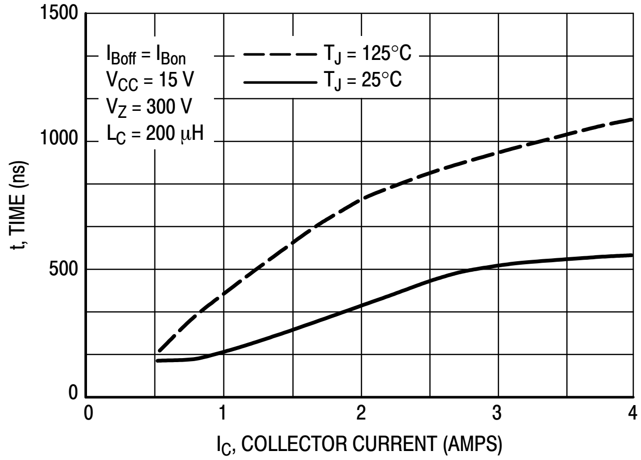


Figure 19. Inductive Switching, t_c @ I_C/I_B = 10

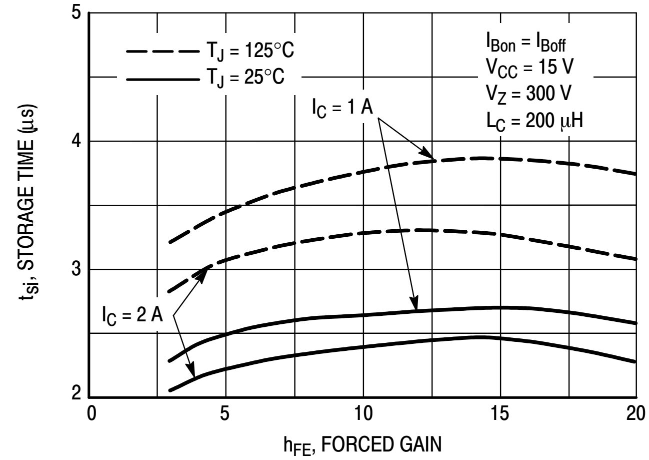


Figure 20. Inductive Storage Time

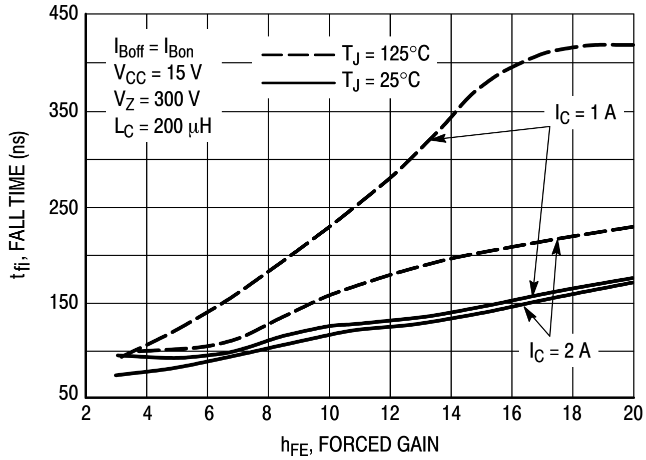


Figure 21. Inductive Fall Time

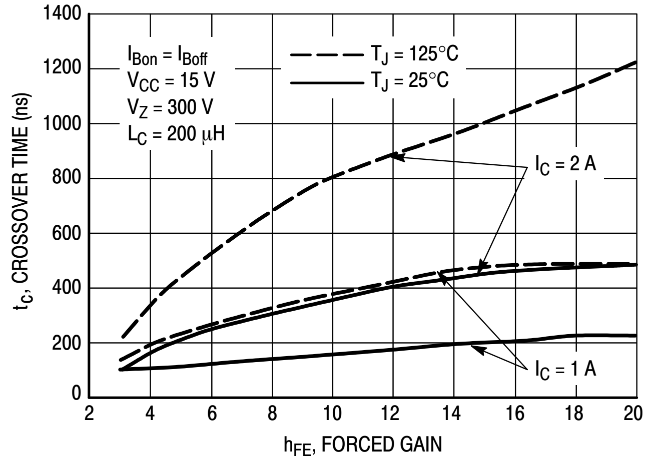


Figure 22. Inductive Crossover Time

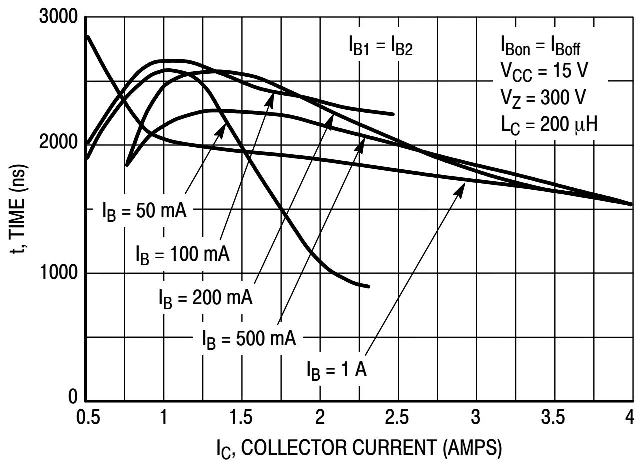


Figure 23. Inductive Storage Time, t_{si}

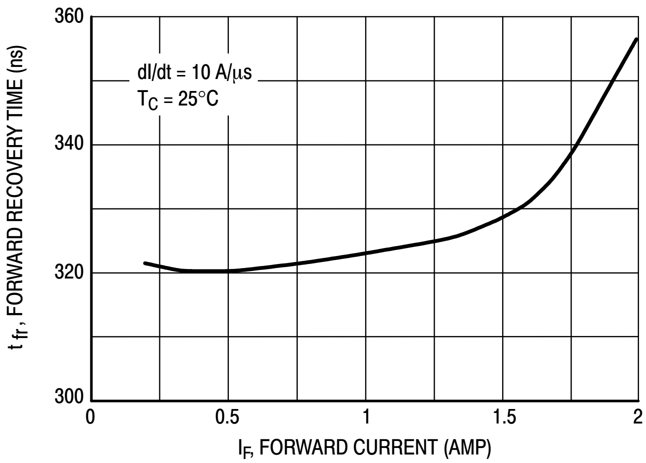


Figure 24. Forward Recovery Time t_{fr}

TYPICAL SWITCHING CHARACTERISTICS

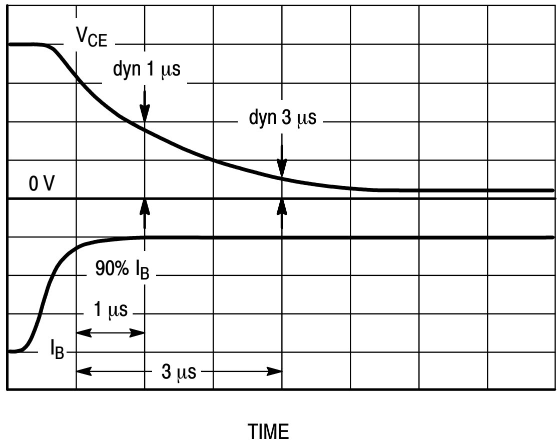


Figure 25. Dynamic Saturation Voltage Measurements

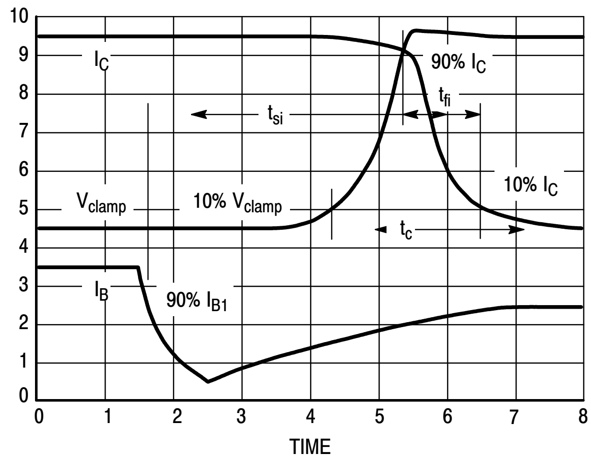


Figure 26. Inductive Switching Measurements

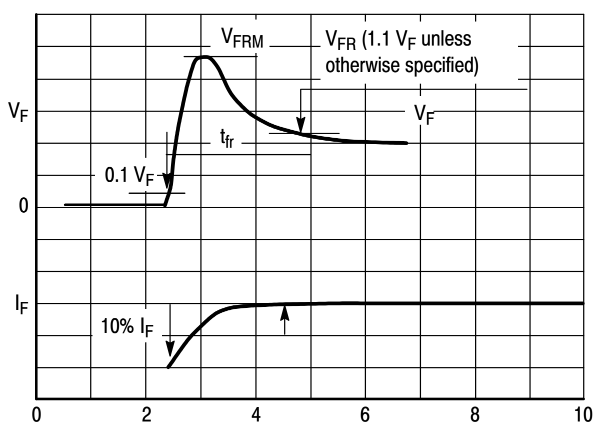
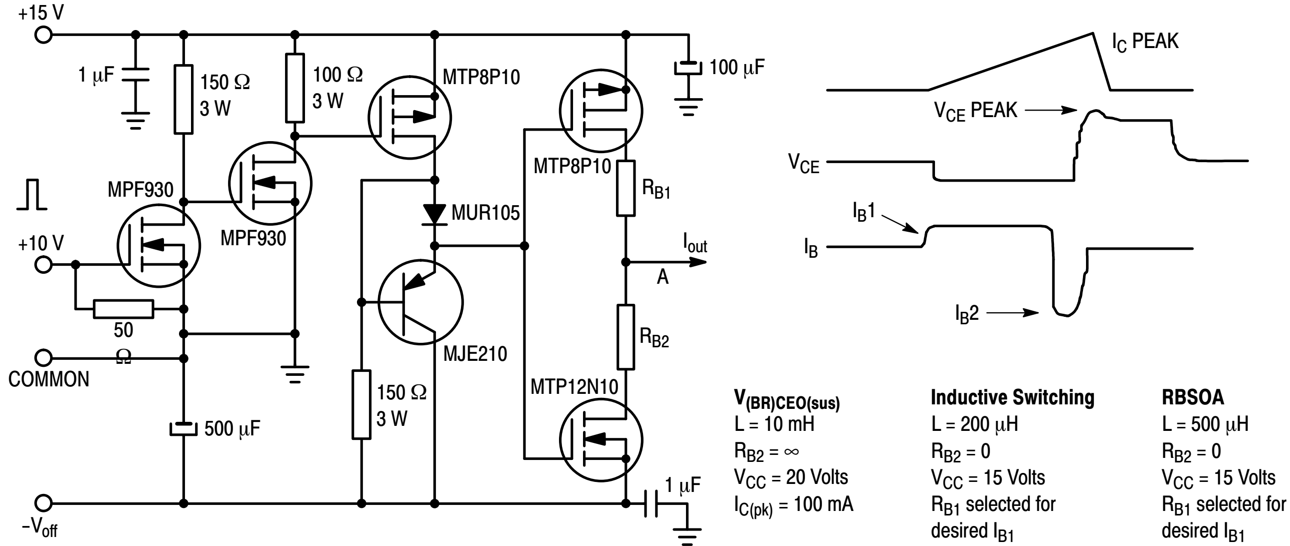


Figure 27. t_{fr} Measurements

TYPICAL SWITCHING CHARACTERISTICS

Table 1. Inductive Load Switching Drive Circuit



TYPICAL CHARACTERISTICS

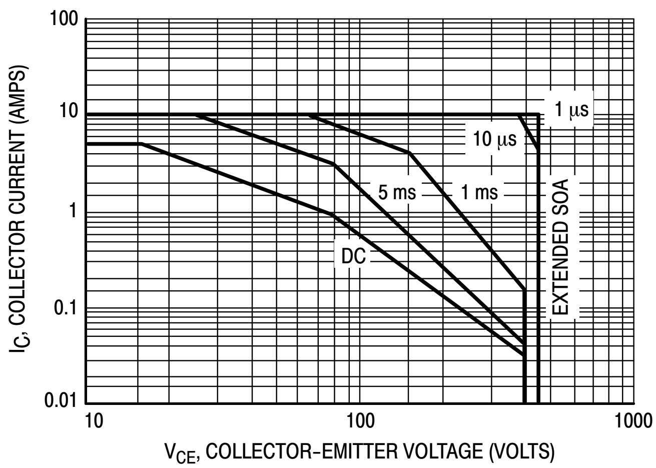


Figure 28. Forward Bias Safe Operating Area

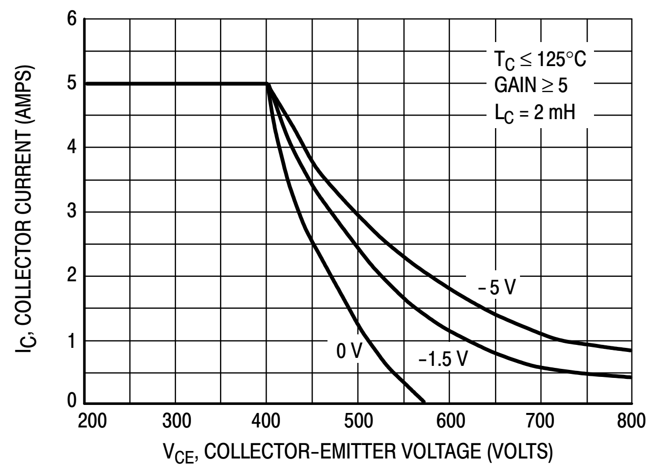


Figure 29. Reverse Bias Safe Operating Area

TYPICAL CHARACTERISTICS

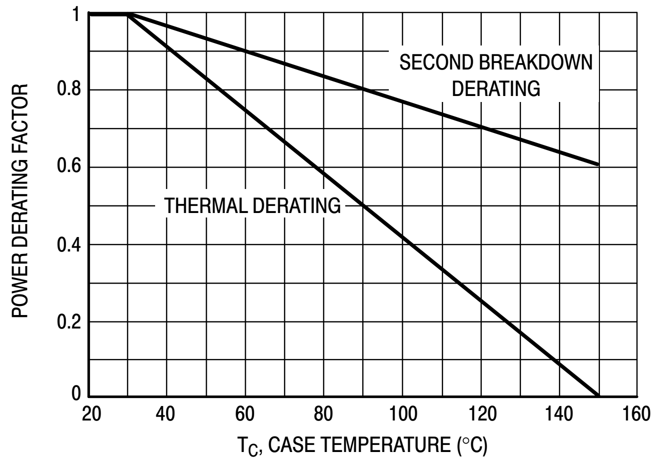


Figure 30. Forward Bias Power Derating

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C-V_{CE} limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate. The data of Figure 28 is based on T_C = 25°C; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when T_C > 25°C. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 28 may be found at any case temperature by using the appropriate curve on Figure 30.

$T_{J(pk)}$ may be calculated from the data in Figure 31. At any case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown. For inductive loads, high voltage and current must be sustained simultaneously during turn−off with the base to emitter junction reverse biased. The safe level is specified as a reverse biased safe operating area (Figure 29). This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode.

TYPICAL THERMAL RESPONSE

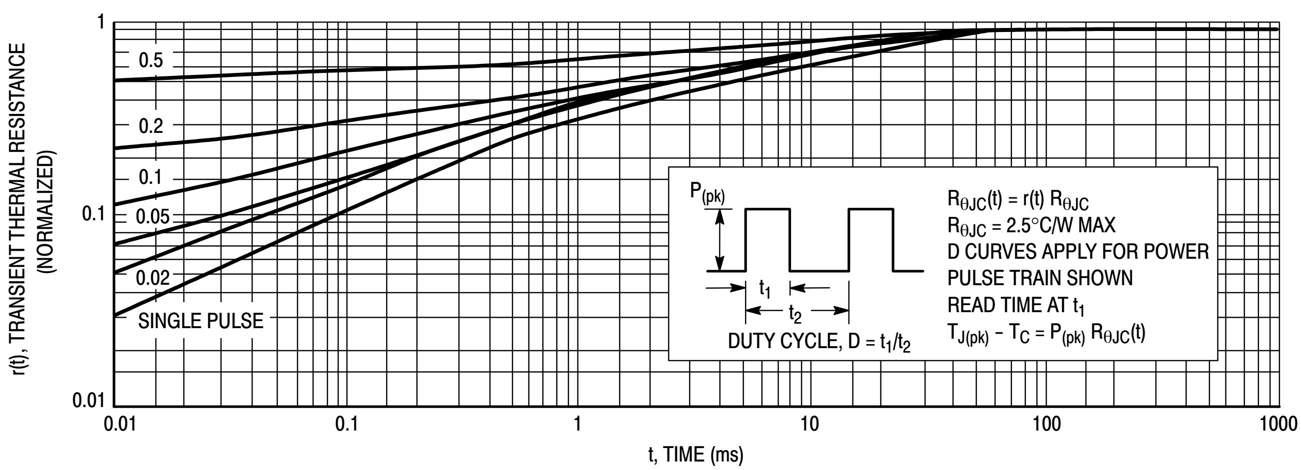
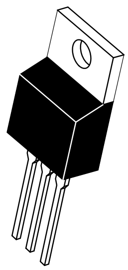


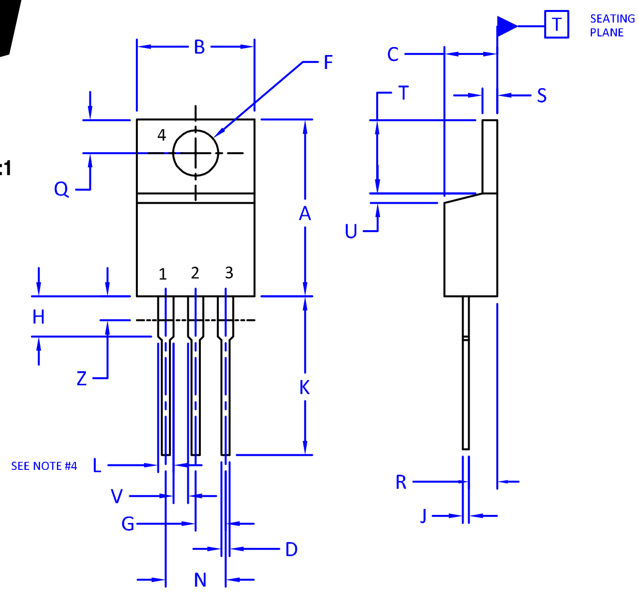
Figure 31. Typical Thermal Response ($Z_{\theta JC}(t)$) for BUL45D2



SCALE 1:1

TO−220
CASE 221A−09
ISSUE AJ

DATE 05 NOV 2019



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.
2. CONTROLLING DIMENSION: INCHES
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.
4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCHES		MILLIMETERS	
DIM	MIN.	MAX.	MIN.	MAX.
A	0.570	0.620	14.48	15.75
B	0.380	0.415	9.66	10.53
C	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.60	4.09
G	0.095	0.105	2.42	2.66
H	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.41
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	----	1.15	---
Z	----	0.080	---	2.04

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:
PIN 1. BASE
2. EMITTER
3. COLLECTOR
4. EMITTER

STYLE 3:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

STYLE 4:
PIN 1. MAIN TERMINAL 1
2. MAIN TERMINAL 2
3. GATE
4. MAIN TERMINAL 2

STYLE 5:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 6:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

STYLE 7:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE

STYLE 8:
PIN 1. CATHODE
2. ANODE
3. EXTERNAL TRIP/DELAY
4. ANODE

STYLE 9:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 10:
PIN 1. GATE
2. SOURCE
3. DRAIN
4. SOURCE

STYLE 11:
PIN 1. DRAIN
2. SOURCE
3. GATE
4. SOURCE

STYLE 12:
PIN 1. MAIN TERMINAL 1
2. MAIN TERMINAL 2
3. GATE
4. NOT CONNECTED

DOCUMENT NUMBER:	98ASB42148B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	TO−220	PAGE 1 OF 1

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT
North American Technical Support:
Voice Mail: 1 800−282−9855 Toll Free USA/Canada
Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:
Phone: 00421 33 790 2910
For additional information, please contact your local Sales Representative

◊